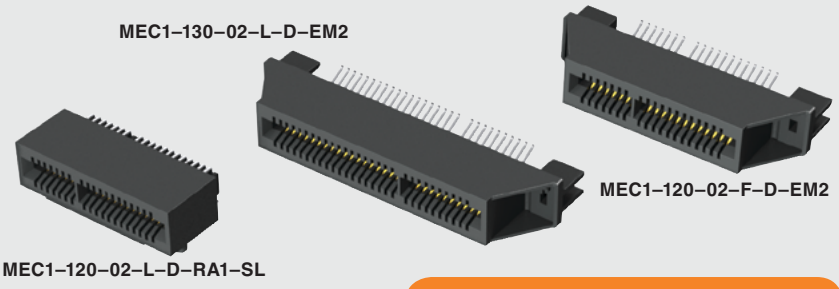
samtec



(1.00 mm) .0394"

MEC1-RA, MEC1-EM SERIES

RIGHT-ANGLE/EDGE MOUNT SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1-RA

Insulator Material: Black LCP
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50 µ" (1.27 µm) Ni
Current Rating: 1.6 A per pin (2 adjacent pins powered)
Operating Temp Range: -55 °C to +125 °C
Insertion Depth: (5.84 mm) .230" to (8.13 mm) .320"
RoHS Compliant: Yes

PROCESSING

Lead–Free Solderable: Yes
SMT Lead Coplanarity: (0.10 mm) .004" max (05-40) (0.15 mm) .006" max (50-70)* *(.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

MEC1 - 1 - POSITIONS PER ROW - CARD SLOT - PLATING OPTION - D - RA1 - NP - SL

Mates with: (1.60 mm) .062" card

05, 08, 20, 30, 40, 50, 60, 70

–02 = (1.60 mm) .062" thick card

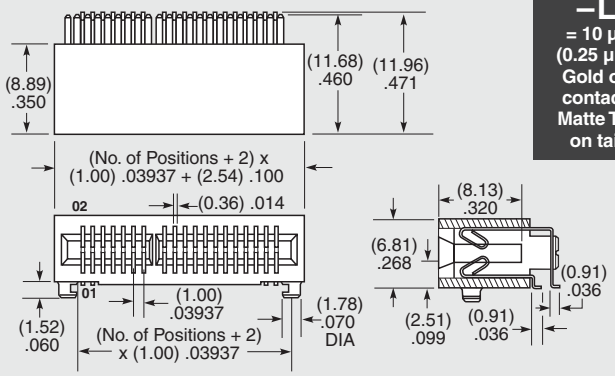
–F = Gold flash on contact, Matte Tin on tail

–L = 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

POSITIONS PER ROW	POLARIZED POSITIONS
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

–NP = No Polarization (8 positions only)
Leave Blank for polarization

Note: While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.



Note: Some sizes, styles and options are non-standard, non-returnable.

ALSO AVAILABLE (MOQ Required)
- Elevated body height
- Other platings

HIGH-SPEED CHANNEL PERFORMANCE

MEC1-RA

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

14 Gbps

APPLICATION

Samtec recommends that pads on the mating board be Gold plated.

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1-EM

Insulator Material: Black LCP
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50 µ" (1.27 µm) Ni
Current Rating: 1.8 A per pin (2 adjacent pins powered)
Operating Temp Range: -55 °C to +125 °C
Insertion Depth: (5.84 mm) .230" to (8.13 mm) .320"
RoHS Compliant: Yes
Lead–Free Solderable: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

MEC1 - 1 - POSITIONS PER ROW - 02 - PLATING OPTION - D - EM2 - NP

Mates with: (1.60 mm) .062" card

05, 08, 20, 30, 40, 50, 60, 70

–F = Gold flash on contact, Matte Tin on tail

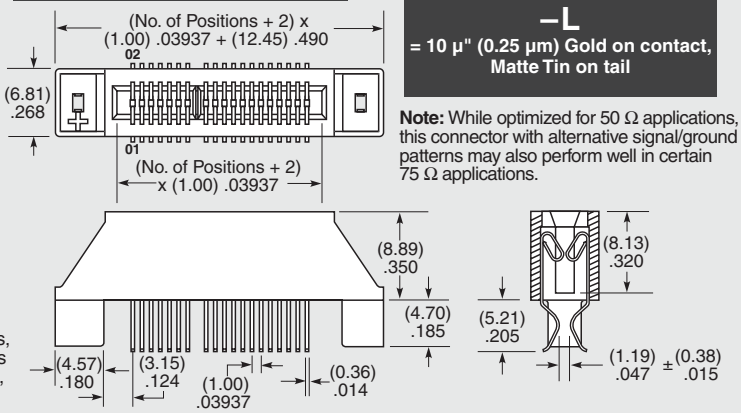
–L = 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail

–NP = No Polarization (8 positions only)
Leave Blank for polarization

Note: While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

POSITIONS PER ROW	POLARIZED POSITIONS
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

ALSO AVAILABLE (MOQ Required)
- Edge mount leads for (0.80 mm) .031" thick board
- Other platings



Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

All parts within this catalog are built to Samtec's specifications.
irements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.

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